

L Number	Hits	Search Text	DB	Time stamp
1	53	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3) with (etch\$3)) and ((grey or gray) same (mask or reticle))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 16:55
2	30	(((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 16:56
3	3204	430/314,323-324.ccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 16:59
4	43	((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 16:59
5	955	((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).ccls.) not 430/314,323-324.ccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:05
6	19	resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)	USPAT; US-PGPUB	2004/01/31 17:05
7	36	430/314,323-324.ccls. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:06
8	13	(resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:07
9	1	((resist or photoresist) and ((microplatform or suspend\$3) same (slop\$3 or inclin\$3 or taper\$3))) and ((grey or gray) with mask)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:08
10	3	(resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:08

11	18	((slop\$3 or inclin\$3 or taper\$3) with (etch\$3) and 430/320.cccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))) not (((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).cccls.) not 430/314,323-324.cccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)) not (430/314,323-324.cccls. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not ((resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))) not ((resist or photoresist) and (microbeam) same (slop\$3 or inclin\$3 or taper\$3)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:09
-	830	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) and (etch\$3)) and ((grey or gray)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/24 16:24
-	35	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 16:54
-	0	((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not us.pc.	DERWENT	2003/07/22 15:32

	0	(430/314, 323-324.ccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))) not us.pc.	DERWENT	2003/07/22 15:32
	2920	430/314, 323-324.ccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/01/17 17:08
	6	((("5962909") or ("5831266") or ("6130109") or ("6025951") or ("6201243") or ("20020043706")).PN.	USPAT; US-PPGPUB	2003/01/17 09:20
	35	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/01/17 15:37
	29	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) with (photomask or mask or reticle))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/01/17 15:37
	58	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/01/17 15:41
	23	((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2004/01/31 16:55
	2919	430/314, 323-324.ccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2004/01/31 16:57
	623	(mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/01/18 11:46
	26	((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2004/01/31 16:58
	884	(photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).ccls.	USPAT; US-PPGPUB	2003/01/18 13:38
	827	((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).ccls.) not 430/314, 323-324.ccls.	USPAT; US-PPGPUB	2003/01/18 13:39
	827	((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).ccls.) not 430/314, 323-324.ccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2004/01/31 17:04
	17	resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)	USPAT; US-PPGPUB	2004/01/31 17:05

-	6636	electroplat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3) 430/314,323-324.ccls. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PGPUB; USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/20 15:35
-	34			2004/01/31 17:06
-	440	(resist or photoresist) and (air adj bridge)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/23 17:03
-	210	(resist or photoresist) same (air adj bridge)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/23 17:04
-	10	(resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:06
-	1	((resist or photoresist) and ((microplatform or suspend\$3) same (slop\$3 or inclin\$3 or taper\$3)) and ((grey or gray) with mask))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:08
-	2	(resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:08
-	900	(resist or photoresist) and ((microplatform or suspend\$3) same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/24 11:20

	16	<p>((slop\$3 or inclin\$3 or taper\$3) with (etch\$3)) and 430/320.cccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))) not (((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).cccls.) not 430/314,323-324.cccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)) not (430/314,323-324.cccls. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not ((resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))) not ((resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3)))</p>	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:09
	45	<p>((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))</p>	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/01/31 17:09
	0	<p>((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not us.pc.</p>	DERWENT	2003/07/22 15:32
	0	<p>(430/314,323-324.cccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))) not us.pc.</p>	DERWENT	2003/07/22 15:32

	26	((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))))	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2004/01/31 17:10
	3048	430/314,323-324.ccls. not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))))	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2004/01/31 17:11
	36	((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2004/01/31 17:11
	915	((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).ccls.) not 430/314,323-324.ccls. not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))))	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2003/07/22 15:40
	18	resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2003/07/22 15:40
	36	430/314,323-324.ccls. and (planarization adj layer) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))))	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2003/07/22 15:41
	11	((resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3)))	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2003/07/22 15:41
	1	((resist or photoresist) and ((microplatform or suspend\$3) same (slop\$3 or inclin\$3 or taper\$3))) and ((grey or gray) with mask)	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2003/07/22 15:41
	2	((resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3)))	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2003/07/22 16:18

	17	<p>((slop\$3 or inclin\$3 or taper\$3) with (etch\$3)) and 430/320.cccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))) not (((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).cccls.) not 430/314,323-324.cccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)) not (430/314,323-324.cccls. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not ((resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))) not ((resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3)))</p>	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:43
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